We Claim:

1. A method of bonding components, which comprises:

preparing a first bond area on a first component;

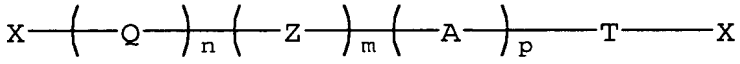
applying a poly-o-hydroxyamide of a general Formula I on the first bond area;

preparing a second area on a second component;

applying the second bond area to the poly-o-hydroxyamide applied to the first bond area to produce an adhesive assembly; and

heating the adhesive assembly to cyclicize the poly-o-hydroxyamide to a polybenzoxazole;

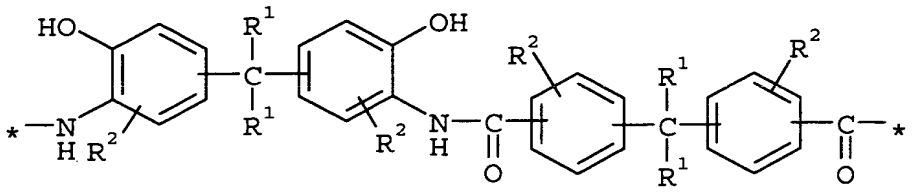
the general formula I having the following structure:



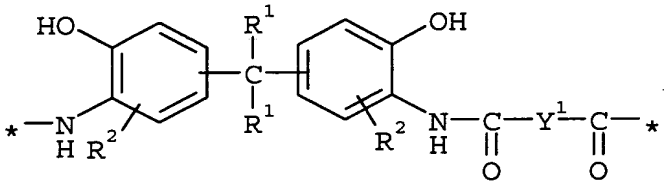
Formula I

where

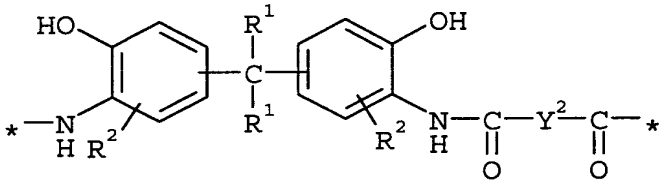
Q is



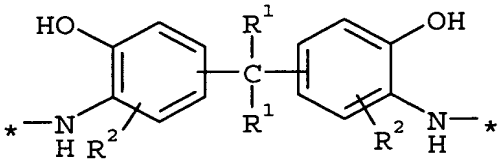
Z is



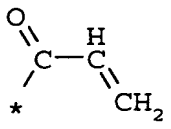
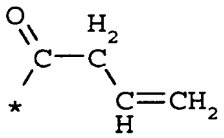
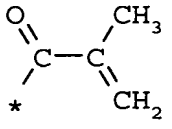
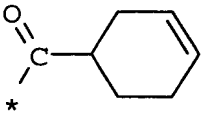
A is

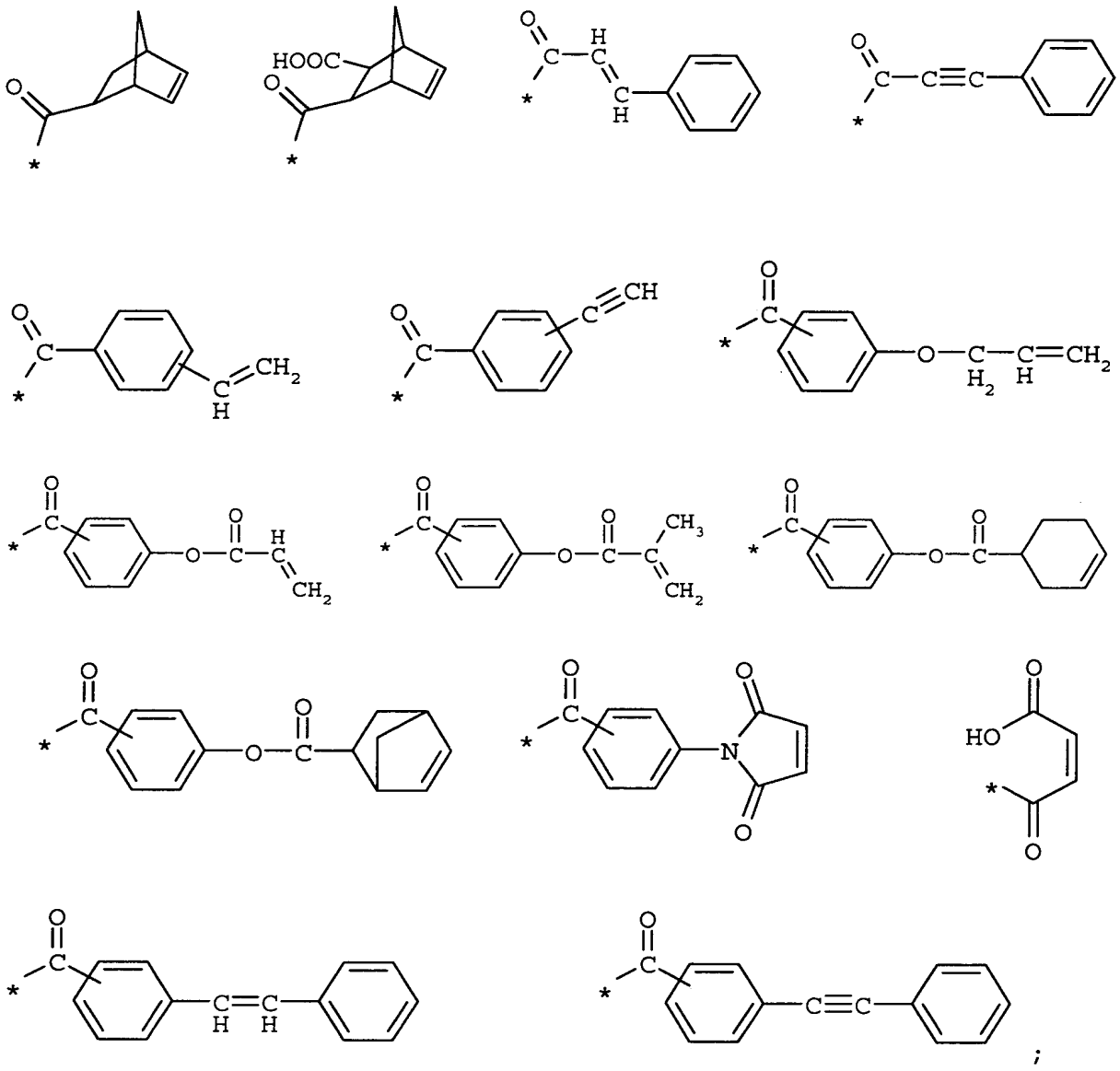


T is



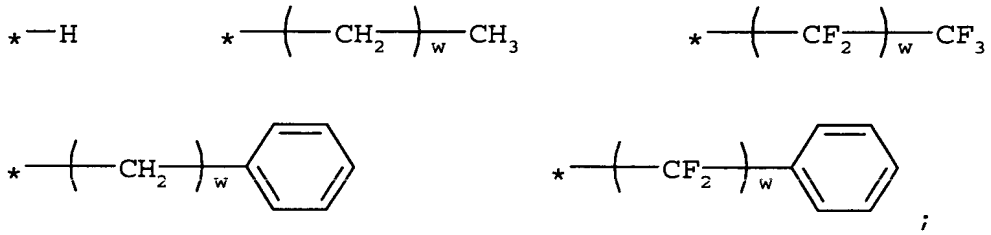
X is a radical selected from the group consisting of



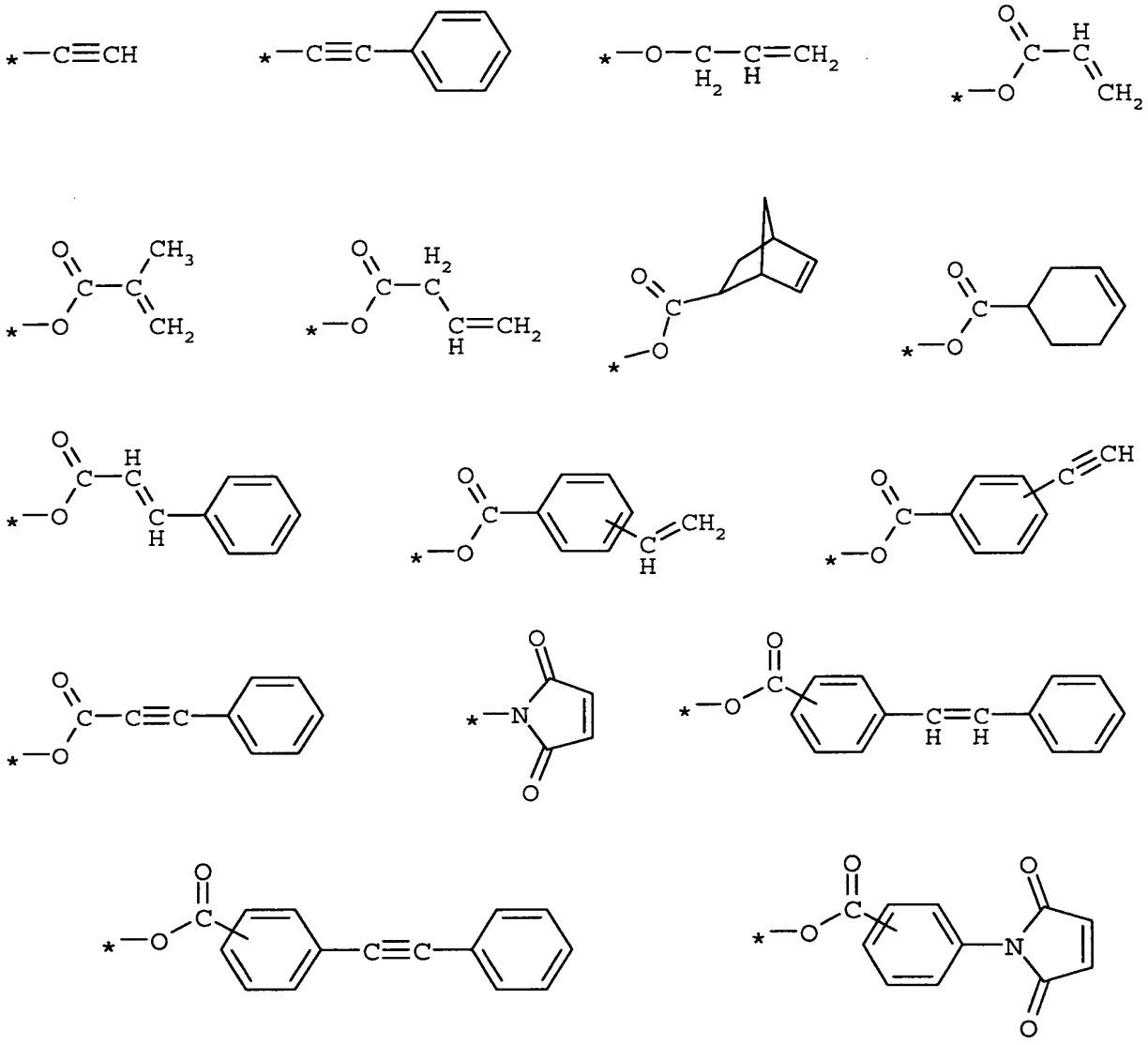
;

R^1 is a radical selected from the group consisting of



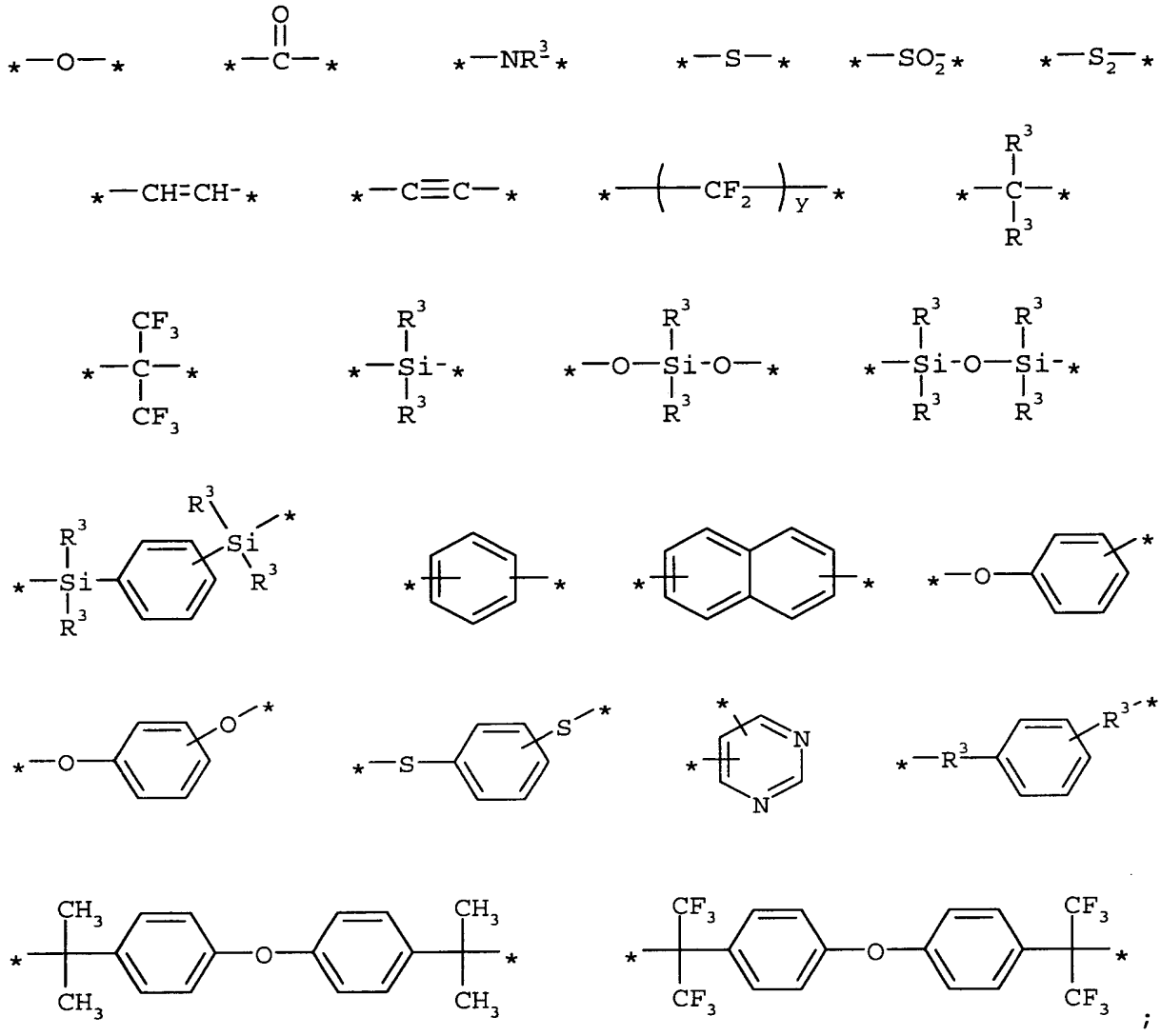
;

R^2 is a radical selected from the group consisting of a hydrogen atom, a trifluoromethyl radical, an alkyl radical having from 1 to 10 carbon atoms,



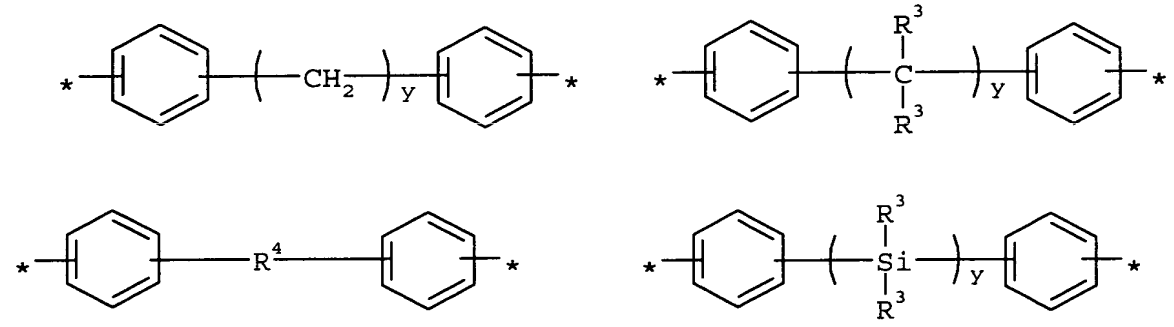
R^3 is an alkyl radical having 1 to 10 carbon atoms or an aryl radical having 5 to 22 carbon atoms;

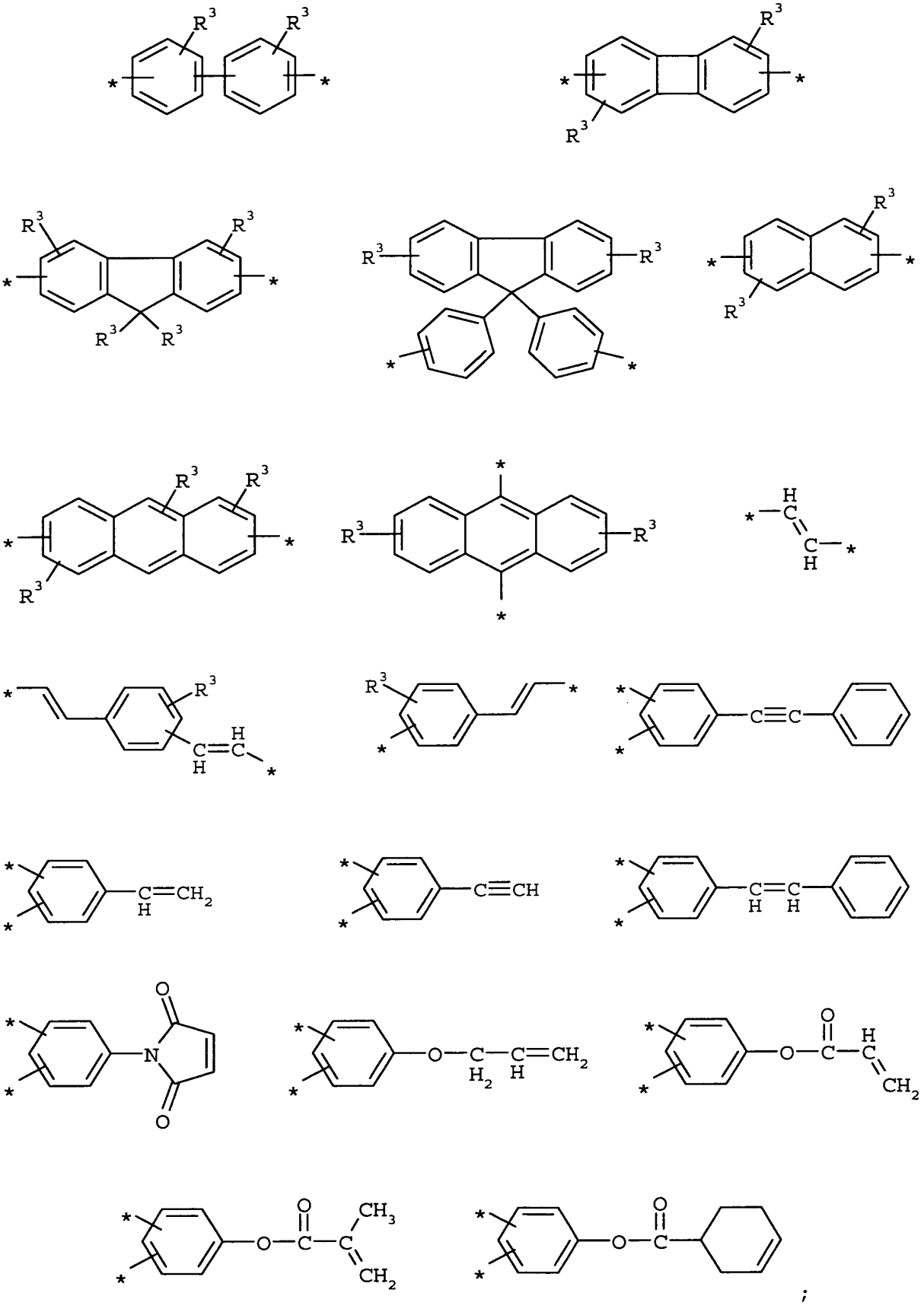
R^4 is a divalent radical selected from the group consisting of



;

Y^1 and Y^2 each independently of one another are a radical selected from the group consisting of





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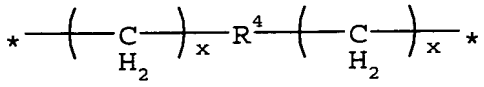

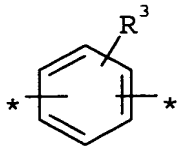

where if R^4 = $-CH_2-$ x = 0 - 10, and additionally

n is an integer between 1 and 100;

m is an integer between 1 and 100;

p is an integer between 0 and 50;

x is an integer between 1 and 10;

y is an integer between 1 and 10; and

w is an integer between 0 and 10.

2. The method according to claim 1, which further comprises additionally applying the poly-o-hydroxyamide of the general formula I to the second bond area to produce the adhesive assembly from the poly-o-hydroxyamide-covered first bond area and the poly-o-hydroxyamide-covered second bond area.

3. The method according to claim 1, where R^1 is a trifluoromethyl radical.

4. The method according to claim 1, which further comprises applying the poly-o-hydroxyamide in solution in a solvent to the first bond area.

5. The method according to claim 2, which further comprises applying the poly-o-hydroxyamide in solution in a solvent to the first and the second bond area.

6. The method according to claim 1, which further comprises adding a conductive material to the poly-o-hydroxyamide.

7. The method according to claim 6, which further comprises using carbon black as the conductive material.

8. The method according to claim 1, wherein the poly-o-hydroxyamide of the formula I is cyclized by heating the adhesive assembly to a temperature of more than 400°C.

9. The method according to claim 1, wherein the adhesive assembly is heated under a reduced pressure.

10. The method according to claim 9, wherein the reduced pressure is less than one atmosphere.

11. The method according to claim 1, which further comprises bridging the adhesive assembly with a conductive paste.

12. The method according to claim 1, which further comprises constructing the first and second components from different materials.

13. The method according to claim 1, wherein the first and second components are formed by constituents of an X-ray image intensifier.

14. The method according to claim 13, which further comprises selecting the constituents of the X-ray image intensifier from the group consisting of vacuum vessel, input screen, support ring, insulator sleeve, anode support, and anode.